() IDT.

QUICKSWITCH[®] PRODUCTS HIGH-SPEED 32-BIT BUS EXCHANGE SWITCH IN MILLIPAQ™

IDTQS34X383

FEATURES:

- 5Ω switches connect inputs to outputs
- Zero propagation delay
- Direct bus connect
- Live insertion capability
- Low power CMOS proprietary technology
- Bus exchange allows nibble swap
- TTL-compatible control inputs
- Available in 80-pin Millipaq package

DESCRIPTION:

The QS34X383 provides four sets of eight high-speed CMOS TTLcompatible bus switches. The low ON resistance (5 Ω) of the QS34X383 allows inputs to be connected to outputs without adding propagation delay and without generating additional ground bounce noise. The Bus Enable ($\overline{\text{BEx}}$) signals turn the switches on. The Bus Exchange (BXx) signals provide nibble swap of the AB and CD pairs of signals. This exchange configuration allows byte swapping of buses in systems. It can also be used as a 16-bit 2-to-1 multiplexer and to create low delay barrel shifters, etc. The QS34X383 is characterized for operation at -40°C to +85°C.

FUNCTIONAL BLOCK DIAGRAM



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INDUSTRIAL TEMPERATURE RANGE

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PIN CONFIGURATION

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BE1		1	$\mathbf{\tilde{\mathbf{v}}}$	80	b	Vcc
Co		2		79	Ь	D3
Ao		3		78	b	B3
B0		4		77	þ.	Аз
D0	Γ	5		76	b	Сз
C1		6		75	þ	D2
A1	Π	7		74	Þ	B2
B1	Γ	8		73	Þ	A2
D1	Π	9		72	Þ	C2
GND	Π	10		71	Þ	BX1
$\overline{BE}\overline{2}$	Γ	11		70	Þ	Vcc
C4	П	12		69	Þ	D7
A4	Γ	13		68	Þ	B7
B4	Γ	14		67	Þ	A7
D4	П	15		66	Þ	C7
C5	Π	16		65	Þ	D6
A5	Π	17		64	Þ	B6
B5	Γ	18		63	Þ	A6
D5	Π	19		62	Þ	C6
GND	Π	20		61	Þ	BX2
BE3	П	21		60	Þ	Vcc
C8	Π	22		59	Þ	D11
A8	Γ	23		58		B11
B8	Π	24		57		A11
D8	Π	25		56	Þ	C11
C9	Π	26		55	ρ.	D10
A9	Γ	27		54		B10
B9	Π	28		53	ρ.	A10
D9	Π	29		52	ρ.	C10
GND	Π	30		51	þ.	ВХ3
$\overline{BE4}$	Γ	31		50		Vcc
C12		32		49		D15
A12		33		48	Ρ	B15
B12		34		47	Ρ	A15
D12		35		46		C15
C13		36		45	2	D14
A13		37		44	Р	B14
B13	Γ	38		43	Р	A14
D13		39		42	Р	C14
GND	Γ	40		41	ρ	BX4

MILLIPAQ TOP VIEW

INDUSTRIAL TEMPERATURE RANGE

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Description	Max	Unit
VTERM ⁽²⁾	Supply Voltage to Ground	–0.5 to +7	V
VTERM ⁽³⁾	DC Switch Voltage Vs	–0.5 to +7	V
VTERM ⁽³⁾	DC Input Voltage VIN	–0.5 to +7	V
VAC	AC Input Voltage (pulse width \leq 20ns)	-3	V
Ιουτ	DC Output Current	120	mA
Рмах	Maximum Power Dissipation (TA = 85°C)	1.4	W
Tstg	Storage Temperature	–65 to +150	°C

NOTE:

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

2. Vcc terminals.

3. All terminals except Vcc.

CAPACITANCE

(TA = +25°C, f = 1.0MHz, VIN = 0V, VOUT = 0V)

Pins	Max. ⁽¹⁾	Unit
Control Pins	8	pF
Quickswitch Channels (Switch OFF)	8	pF

NOTE:

1. This parameter is measured at characterization but not tested.

PIN DESCRIPTION

Pin Names I/O		Description
Ax, Bx	I/O	Buses A, B
Cx, Dx	I/O	Buses C, D
BEx	I	Bus Switch Enable
BXx	I	Bus Exchange

FUNCTION TABLE(1)

BEx	BXx	Ax	Вх	Function
Н	Х	Z	Z	Disconnect
L	L	Сх	Dx	Connect
L	Н	Dx	Сх	Exchange

NOTE:

1. H = HIGH Voltage Level L = LOW Voltage Level

L = LOW VoltagX = Don't Care

Z = High-Impedance

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified: Industrial: TA = -40°C to +85°C, Vcc = $5.0V \pm 5\%$

Symbol	Parameter	Test Conditions	Min.	Typ. ⁽¹⁾	Max.	Unit
Vih	Input HIGH Level	Guaranteed Logic HIGH for Control Pins	2	—	—	V
VIL	Input LOW Level	Guaranteed Logic LOW for Control Pins	—	—	0.8	V
lin	Input LeakageCurrent (Control Inputs)	$0V \le VIN \le VCC$, Control Inputs	_	—	±5	μA
loz	Off-State Output Current (Hi-Z)	$0V \le VOUT \le Vcc$, Switches OFF	_	—	±5	μA
Ron	Switch ON Resistance ^(2,3) Vcc = Min., VIN = 0V, ION = 30mA		_	6	8	Ω
		VCC = Min., VIN = 2.4V, ION =15mA	—	12	17	

NOTES:

1. Typical values are at Vcc = 5.0V, TA = 25°C.

2. Max value of Ron is guaranteed but not production tested.

3. Measures by voltage drop between the AB and CD pin at the indicated current through the switch. ON resistance is determined by the lower of the voltages on the two (A or B, C or D) pins.

TYPICAL ON RESISTANCE vs Vin AT Vcc = 5V



(Volts)

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾	Max.	Unit
lccq	Quiescent Power Supply Current	Vcc = Max., \overline{BEx} = GND or Vcc, f = 0	6	mA
Δlcc	Power Supply Current per Control Input HIGH (2)	Vcc = Max., BEx = 3.4V, f = 0	2.5	mA
ICCD	Dynamic Power Supply Current per MHz ⁽³⁾	Vcc = Max., A and B pins open	0.25	mA/MHz
		Control Inputs Toggling at 50% Duty Cycle		

NOTES:

1. For conditions shown as Min. or Max., use the appropriate values specified under DC Electrical Characteristics.

2. Per TLL driven input (VIN = 3.4V, control inputs only). A-D pins do not contribute to ∆lcc.

3. This current applies to the control inputs only and represents the current required to switch internal capacitance at the specified frequency. The A and B inputs generate no significant AC or DC currents as they transition. This parameter is guaranteed but not production tested.

SWITCHING CHARACTERISTICS OVER OPERATING RANGE

 $T_A = -40^{\circ}C$ to +85°C, Vcc = 5.0V ± 5%;

CLOAD = 50pF, RLOAD = 500Ω unless otherwise noted.

Symbol	Parameter	Min. ⁽¹⁾	Тур.	Max.	Unit
tPLH	Data Propagation Delay ^(2,3)	—	—	0.25	ns
t PHL	AxBx to CxDx, CxDx to AxBx				
tPZL	Switch Turn-on Delay	1.5	—	6.5	ns
tРZH	BEx to Ax, Bx, Cx, Dx				
tPLZ	Switch Turn-off Delay ⁽²⁾	1.5	—	5.5	ns
tPHZ	BEx to Ax, Bx, Cx, Dx				
tвx	Switch Multiplex Delay ⁽²⁾	1.5	—	6.5	ns
	BX to Ax, Bx, Cx, Dx				
Qci	Charge Injection ^(4,5)	—	1.5	—	рC

NOTES:

1. Minimums are guaranteed but not production tested.

2. This parameter is guaranteed but not production tested.

3. The bus switch contributes no propagation delay other than the RC delay of the ON resistance of the switch and the load capacitance. The time constant for the switch alone is of the order of 0.25ns for C_L = 50pF. Since this time constant is much smaller than the rise and fall times of typical driving signals, it adds very little propagation delay to the system. Propagation delay of the bus switch, when used in a system, is determined by the driving circuit on the driving side of the switch and its interaction with the load on the driven side.

4. Measured at switch turn off, A to C, load = 50pF in parallel with 10 meg scope probe, VIN at I = 0V.

5. Measured at switch turn off through bus multiplexer, A to C ≥ A to D, B connected to C, load = 50pF in parallel with 10 meg scope probe, VIN at A = 0V. Charge injection is reduced because the injection from the turn off of the A to C switch is compensated by the turn on of the B to C switch.



Datasheet Document History

02/20/09Pg. 5Updated the ordering information by removing the "IDT" notation.08/15/12Pg. 5Updated the ordering information by removing the non RoHS part and by addingTape and Reel information.

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